Ref #	Hits	Search Query	DBs.	Default Operator	Plurals	Time Stamp
S1	185	JANG-SE-YOUNG-, in. JANG-S-Y-, in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 12:11
S2	3	JANG-SE-YOUNGin. JANG-S-Y in.	US-PGPUB; USPAT	OR	ON	2005/06/23 09:47
S3	2	jp-10018949-\$.did.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 09:47
S5	17853	solder near bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 12:13
S6	185	JANG-SE-YOUNGin. JANG-S-Y in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:10
S21	836454	resist photoresist photo-resist photosensitive photo-sensitive photocur\$5 photo-cur\$5 photo near cur\$5 (sensitive near (photo light energy radiation))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 12:22
S22	211972	solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 12:22
S23	1308243	cu copper	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 12:23
S25	1621	ubm! under-bump-metal\$8 ((under adj bump under-bump) adj metal\$8)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:09
S26	12080	(pb lead) near free pb-free lead-free	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:01

S28	1641727	(pb lead)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:01
S30	1808	pb/sn sn/pb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:09
S31	<b>445</b>	ball-limit\$3-metal\$8 (ball-limit\$3 ball adj limit\$3) adj metal\$8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:10
S32	3	JANG-SE-YOUNGin. JANG-S-Y in.	US-PGPUB; USPAT	OR	ON	2005/06/23 13:10
S33	2	S6 and (S25 S31)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/06/23 13:11
S34	182	S21 same (S25 S31) same S23	US-PGPUB; USPAT	OR	ON	2005/06/23 13:35
S35	7	S34 same S26	US-PGPUB;	OR	ON	2005/06/23 13:25
S36	7928	sncu snag snagcu snbi snzi	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:26
S37	136	S22 near3 S36	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:26
S38	3163	S22 near3 (S26 S36)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:27
S39	6227	430/311,313,314,318.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:28
S40	22	S39 and (S25:S31)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:28

S41	17	S21 and (S25 S31) and S23	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:39
S42	287	(S25 S31) near3 etch\$	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2005/06/23 13:45
S43	. 163	S42 same S21	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:40
S45	3076	S22 near3 S26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:40
S46	11	S43 and (S45 S36)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/06/23 13:45
S47	242	(S25 S31) near3 S23	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:45
S48	39	S47 and (S45 S36)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 13:45
S49	34	S48 not S46	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 14:01
S56	14373	snag agsn (silver near tin) "sn/ag" "ag/sn"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:07
S57	8	S56 with S5 with (known conventional\$3 typical\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:12

S58	24	(time min minute second sec) with temperature with S5 with (known conventional\$3 typical\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:16
S59	2	(time min minute second sec) with temperature with S5 with S56	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:21
S60	81	(time min minute second sec) with temperature with S5 with reflow\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:26
S63	43537	reflow\$3 re-flow\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:28
S64	'41	S63 with S42	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:34
S65	11	S63 with S42 with (before prior)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 16:34
S70	4962	438/612,613,614.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 18:44
S71	120	S70 and S21 and S26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 18:48
S72	3	S70 and S21 and S26 and (S25 and S31)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR .	ON	2005/06/23 18:45
S73	115	S70 and S21 and S26 and S23	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/23 18:49